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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q62494

Ryo KUBOTO, et al.

Appln. No.: 09/817,233

Group Art Unit: 2823

Confirmation No.: 8072

Examiner: Hsien Ming LEE

Filed: March 27, 2001

For: MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE HAVING DRAM  
CAPACITORS

INFORMATION DISCLOSURE STATEMENT  
UNDER 37 C.F.R. §§ 1.97 and 1.98

Commissioner for Patents  
Washington, D.C. 20231

Sir:

In accordance with the duty of disclosure under 37 C.F.R. § 1.56, Applicant hereby  
notifies the U.S. Patent and Trademark Office of the documents which are listed on the attached  
PTO/SB/08 A & B (modified) form and/or listed herein and which the Examiner may deem  
material to patentability of the claims of the above-identified application.

1. Japanese Unexamined Patent Publication No. 11-186524, published July 9, 1997.  
(This reference was previously submitted to the U.S. Patent and Trademark Office  
with an Information Disclosure Statement dated December 4, 2002. Therefore, a  
copy is not enclosed herewith.)
2. Korean Unexamined Patent Application Publication No. 2000-8804, published  
February 15, 2000.

One copy of each of the listed documents is submitted herewith.

The present Information Disclosure Statement is being filed after the later of three  
months from the application's filing date and the mailing date of the first Office Action on the

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KUBOTO et al.  
Appln. No. 09/817,233  
Information Disclosure Statement

merits, but before a Final Office Action, Notice of Allowance, or an action that otherwise closes prosecution in the application (whichever is earlier), and therefore Applicant is filing concurrently herewith a Statement Under 37 C.F.R. § 1.97(e). No fee under 37 C.F.R. § 1.17(p) is required.

In compliance with the concise explanation requirement under 37 C.F.R. § 1.98(a)(3) for foreign language documents, Applicant encloses herewith a copy of a Korean Office Action dated January 30, 2003 with a Japanese translation thereof. Also enclosed is an English translation of the pertinent portions of the Japanese translation which cites such documents and indicates the degree of relevance found by the foreign patent office.

The submission of the listed documents is not intended as an admission that any such document constitutes prior art against the claims of the present application. Applicant does not waive any right to take any action that would be appropriate to antedate or otherwise remove any listed document as a competent reference against the claims of the present application.

Respectfully submitted,



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WASHINGTON OFFICE



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PATENT TRADEMARK OFFICE

Date:

**APR 15 2003**

Ref. Q62494

All of the claims of the invention of the present application are related to an invention of a manufacturing method of a system on-chip semiconductor device mainly characterized by removing the polysilicon film and HSG on the upper surface of the interlayer film, and by maintaining the polysilicon film and HSG on the inner walls of the cylinder. However, described in the Abstract, Embodiment 1, and Figures 1 through 13 of Japanese Unexamined Patent Application Publication H11-186524 (disclosed on July 9, 1997), as well as the Abstract, Embodiment 1, Claim 1, and Figures 1a through 1e of Korean Unexamined Patent Application Publication 2000-8804 (disclosed on February 15, 2000) is the fact that the polysilicon film and HSG on the upper surface of the interlayer insulating film are removed, and the polysilicon film and HSG on the inner walls of the cylinder are maintained. The invention of the present application could be easily invented based on the well-known technology of Japanese Unexamined Patent Application Publication H11-186524 (disclosed on July 9, 1997) and Korean Unexamined Patent Application Publication 2000-8804 (disclosed on February 15, 2000).

(Attachments)

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|--------------|---|
| Attachment 1 | Japanese Unexamined Patent Application Publication H11-186524 (disclosed on July 9, 1997)   |
| Attachment 2 | Korean Unexamined Patent Application Publication 2000-8804 (disclosed on February 15, 2000) |



Substitute for Form 1449 A &amp; B/PTO

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Complete if Known

Application Number	09/817,233
Confirmation Number	8072
Filing Date	March 27, 2001
First Named Inventor	Ryo KUBOTO
Art Unit	2823
Examiner Name	Hsien Ming LEE
Attorney Docket Number	Q62494

Sheet 1 of 1

**U.S. PATENT DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number	Kind Code <sup>2</sup> (if known)		
		US			
		US			
		US			
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**FOREIGN PATENT DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document			Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Translation <sup>6</sup>
		Country Code <sup>3</sup>	Number <sup>4</sup>	Kind Code <sup>5</sup> (if known)			
		KR	2000-8804	A	02-15-2000		No

**OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.	Translation <sup>6</sup>

Examiner Signature

Date Considered

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup>Applicant's unique citation designation number (optional). <sup>2</sup>See Kind Codes of USPTO Patent Documents at www.uspto.gov, MPEP 901.04 or in the comment box of this document. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST. 3). <sup>4</sup>For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to indicate here if English language Translation is attached.